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We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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# HCV1707

## High current power inductors



#### **Product features**

- · Flat-wire construction
- · Low DCR, high efficiency
- Secure 3 terminal mounting
- 17.8 mm x 14.35 mm footprint surface mount package in a 6.9 mm height
- · Ferrite core material
- Moisture Sensitivity Level: 1

#### **Applications**

• Compatible with Picor® Cool-Power® ZVS Buck and Buck-Boost Regulator Families

#### **Environmental data**

- Storage temperature range (Component):  $-55~^{\circ}\mathrm{C}$  to  $+125~^{\circ}\mathrm{C}$
- Operating temperature range: -55 °C to +125 °C (ambient plus self-temperature rise)
- Solder reflow temperature:
   J-STD-020 (latest revision) compliant
- Halogen free, lead free, RoHS compliant



Picor® and Cool-Power® are trademarks of Vicor Corporation.



### **Product specifications**

Part Number <sup>7</sup>	OCL¹ (μH) ±10%	FLL² (μH) minimum	I 3 (A)	I <sub>sat</sub> 1 <sup>4</sup> (A)	I <sub>sat</sub> 2 <sup>5</sup> (A)	I <sub>sat</sub> 3 <sup>6</sup> (A)	DCR (mΩ) ±10% @ +20 °C
HCV1707R1-R48-R	0.48	0.42	32	55	68	47	1.7

- 1. Open Circuit Inductance (OCL) Test Parameters: 100 kHz, 0.1 Vrms, 0.0 Adc, +25 °C
- 2. Full Load Inductance (FLL) Test Parameters: 100 kHz, 0.1 Vrms, I<sub>sat</sub>1, +25 °C
- 3. I<sub>ms</sub>: DC current for an approximate temperature rise of 40 °C without core loss. Derating is necessary for AC currents. PCB layout, trace thickness and width, air-flow, and proximity of other heat generating components will affect the temperature rise. It is recommended that the temperature of the part not exceed +125 °C under worst case operating conditions verified in the end application.
- 5. I<sub>sat</sub> 2: Peak current for approximately 2% rolloff @ -55 °C
- 6. I 3: Peak current for approximately 2% rolloff @ +125 °C
- 7. Part Number Definition: HCV1707Rx-Rxxx-R HCV1707= Product code and size

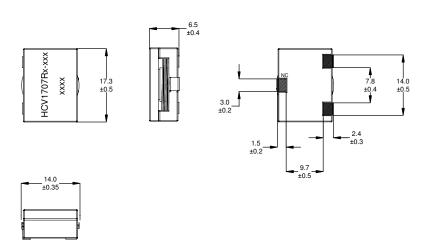
Rx= Version indicator

Rxx= Inductance value in µH, R= decimal point,

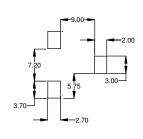
If no R is present last character equals number of zeros

-R suffix = RoHS compliant

#### **Dimensions (mm)**



## Recommended Pad Layout



#### Schematic

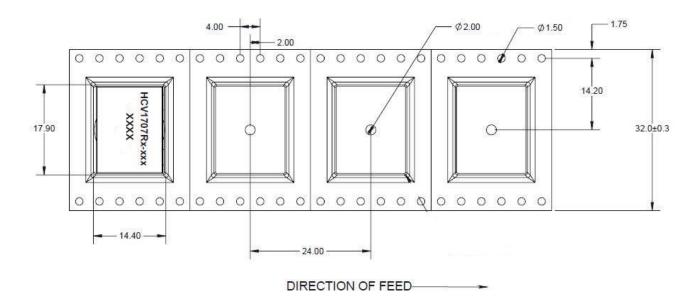


Part marking: HCV1707Rx-Rxx, Rxx= inductance value in uH, R= decimal point, if no R is present last character equals number of zeros xxxx=lot code

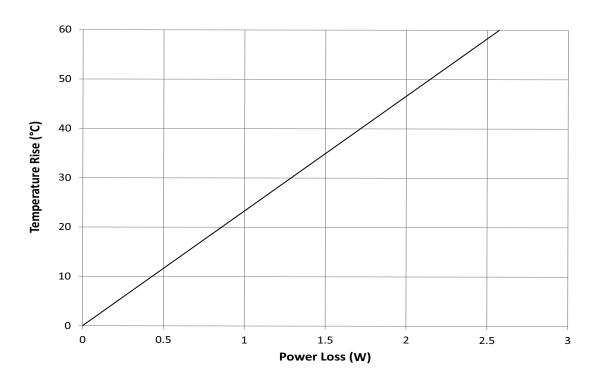
All soldering surface to be coplanar within 0.1 millimeters Tolerances are  $\pm 0.15$  millimeters unless stated otherwise Pad layout tolerances are  $\pm 0.1$  millimeters unless stated otherwise Pin NC is for mounting stability. No connection. Do not route traces or vias underneath the inductor

## Packaging information (mm)

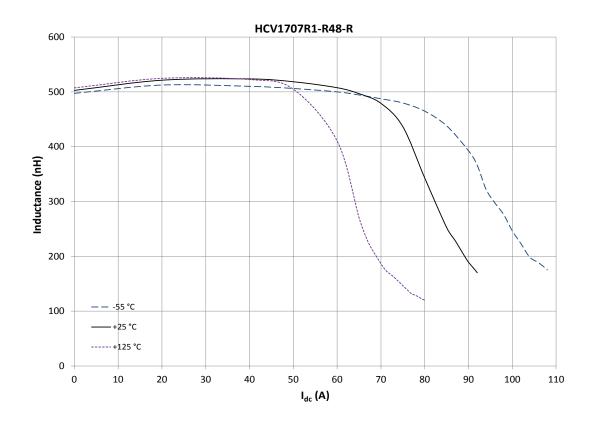
Supplied in tape and reel packaging, 350 parts per 13" diameter reel



### Temperature rise vs. total loss



## Inductance characteristics



## Solder reflow profile

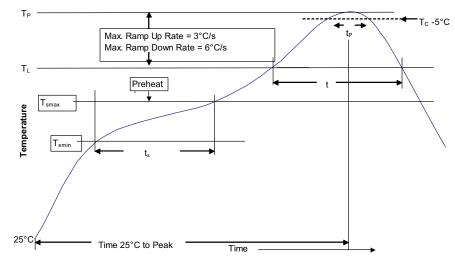


Table 1 - Standard SnPb Solder (T<sub>C</sub>)

Package Thickness	Volume mm3 <350	Volume mm3 ≥350
<2.5mm)	235 °C	220 °C
≥2.5mm	220 °C	220 °C

Table 2 - Lead (Pb) Free Solder (T<sub>C</sub>)

Package Thickness	Volume mm³ <350	Volume mm³ 350 - 2000	Volume mm³ >2000
<1.6mm	260 °C	260 °C	260 °C
1.6 – 2.5mm	260 °C	250 °C	245 °C
>2.5mm	250 °C	245 °C	245 °C

## **Reference JDEC J-STD-020**

Profile Feature	Standard SnPb Solder	Lead (Pb) Free Solder	
Preheat and Soak • Temperature min. (T <sub>smin</sub> )	100 °C	150 °C	
• Temperature max. (T <sub>smax</sub> )	150 °C	200 °C	
• Time (T <sub>smin</sub> to T <sub>smax</sub> ) (t <sub>s</sub> )	60-120 Seconds	60-120 Seconds	
Average ramp up rate T <sub>smax</sub> to T <sub>p</sub>	3°C/ Second Max.	3 °C/ Second Max.	
Liquidous temperature (TL) Time at liquidous (tL)	183 °C 60-150 Seconds	217 °C 60-150 Seconds	
Peak package body temperature (Tp)*	Table 1	Table 2	
Time (t <sub>p</sub> )** within 5 °C of the specified classification temperature (T <sub>c</sub> )	20 Seconds**	30 Seconds**	
Average ramp-down rate (T <sub>p</sub> to T <sub>smax</sub> )	6 °C/ Second Max.	6 °C/ Second Max.	
Time 25 °C to Peak Temperature	6 Minutes Max.	8 Minutes Max.	

 $<sup>^{*}</sup>$  Tolerance for peak profile temperature (T<sub>p</sub>) is defined as a supplier minimum and a user maximum.

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<sup>\*\*</sup> Tolerance for time at peak profile temperature (t<sub>p</sub>) is defined as a supplier minimum and a user maximum.